

NEC

Preliminary User's Manual

IE-703242-G1-EM1

**In-Circuit Emulator Option Board
for V850ES/GB1**

Hardware

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NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

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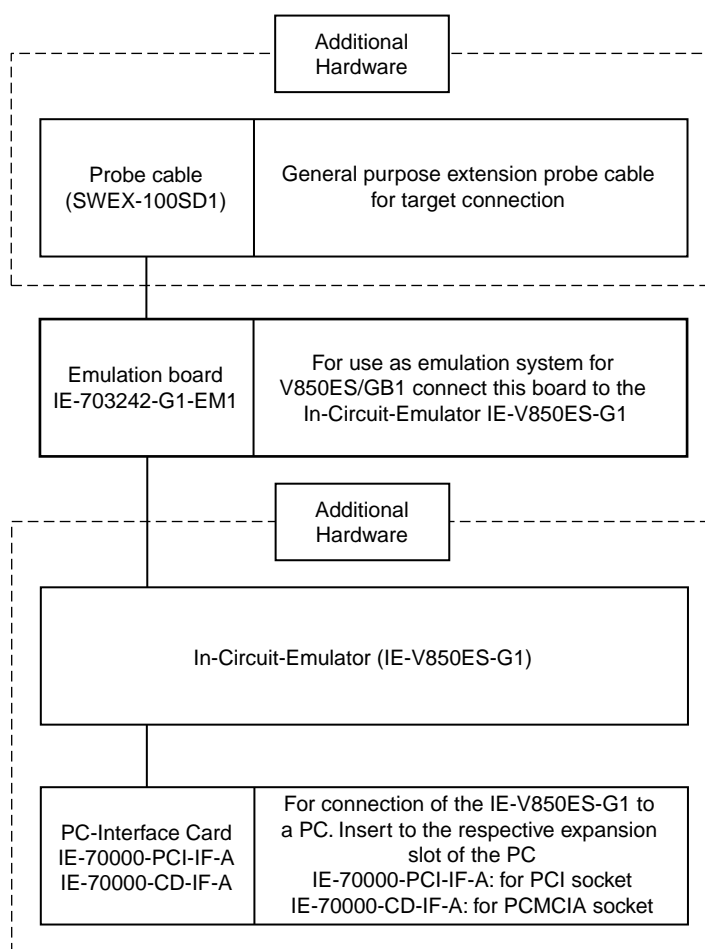
Chapter 1 Overview

The IE-703242-G1-EM1 is an option board for the IE-V850ES-G1 in circuit emulator. Using the IE-703242-G1-EM1 in conjunction with the IE-V850ES-G1, hardware and software developed for V850ES/GB1 can be debugged efficiently.

This manual describes the basic setup procedure and configuration settings of the IE-V850ES-G1 when used together with IE-703242-G1-EM1.

1.1 Hardware Configuration

Figure 1-1: IE-703242-G1-EM1 hardware configuration



1.2 Components of the Emulation System

For order codes of the components that may be used in an emulation system for V850ES/GB1 refer to the following table:

Table 1-1: Components of Emulation System

Component	Order Code	Comment
In-Circuit-Emulator	IE-V850ES-G1	Main board for CPU emulation and trace Notes 1, 2
Emulation board	IE-703242-G1-EM1	Emulation board for V850ES/GB1 Notes 1, 2
Probe cable	SWEX-100SD1	Probe cable for target connection Note 2
Probe to target connector	NQPACK100SD	Board socket for target connection (soldered on target board) Note 2
Probe to target connector	YQPACK100SD	Probe connection (fixed on NQPACK100SD) Note 2
Probe to target connector	YQSOCKET100SDF	Distance socket (optional)
PC interface card	IE-70000-PCI-IF-A	PCI interface card for host connection Note 3
PC interface card	IE-70000-CD-IF-A	PCMCIA interface card for host connection Note 3
Network interface	IE-70000-MC-SV3	Network interface for host connection Note 3

- Notes:**
1. Required for stand alone operation (no target connection)
 2. Required for operation with target hardware
 3. The interfaces are alternative, one is mandatory

1.3 Features (When Connected to IE-V850ES-G1)

Table 1-2: Features of IE-703242-G1-EM1

Parameter	Value
Operation frequency	max. 16 MHz (Main clock)
Operation Temperature range	0 to +40°C
Storage temperature range	-15 to +60°C
Environmental humidity range	10 - 80% RH
Supply voltage	+4.5 V to +5.5 V \pm 5%
Supply current	< 300 mA
Power dissipation	< 1 W (@ 16 MHz)
Weight	< 300 g
Dimensions ^{Note}	205 mm x 140 mm x 20 mm

Note: Please refer to the appendix “Mechanical data”.

1.4 Function Specifications (When Connected to IE-V850ES-G1)

Table 1-3: Functional Specifications of IIE-703242-G1-EM1

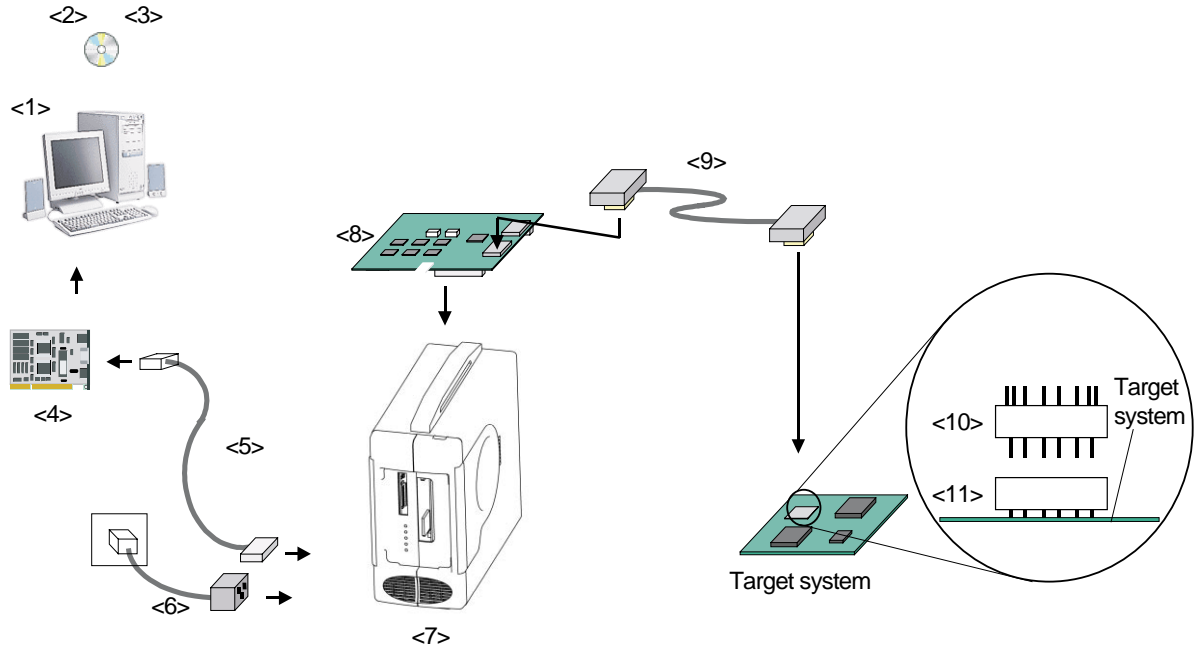
Parameter		Specification
Emulation memory capacity	Internal ROM	1 MB
	User memory	4 MB
Coverage memory capacity for execution/pass detection	Internal ROM	256 KB
	External memory	1 MB
Coverage memory capacity for memory access detection	External memory	1 MB
Coverage memory capacity for branching entry number counting	Internal ROM	256 KB
	External memory	1 MB
Trace memory capacity		168 bits × 32 K frames
Time measurement function		On-chip timer: 3
External logic probe		8-bit external trace possible
		Event setting for trace/break possible
Break function		Event break
		Step execute break
		Forced break
		Fail safe break <ul style="list-style-type: none"> • Illegal access to peripheral I/O • Access to guard space • Write to the ROM space

Caution: Some of the functions may not be supported, depending on the debugger used.

1.5 System Configuration

The system configuration when connecting the IE-V850ES-G1 to the IE-703242-G1-EM1 and a personal computer (PC/AT or compatible) is shown below.

Figure 1-2: System Configuration



- Remark:**
- <1>: PC
 - <2>: Debugger (Sold separately)
 - <3>: Device file (Included with the IE-703242-G1-EM1)
 - <4>: PC interface board (Sold separately)
 - <5>: PC interface cable (Included with the IE-V850ES-G1 [Sold separately])
 - <6>: Power supply cable (Included with the IE-V850ES-G1 [Sold separately])
 - <7>: In-circuit emulator (IE-V850ES-G1: Sold separately)
 - <8>: In-circuit emulator emulation board (IE-703242-G1-EM1: This product)
 - <9>: Extension probe (SWEX-100SD1: Sold separately)
 - <10>: YQPACK100SD (Sold separately)
 - <11>: NQPACK100SD (Sold separately)

1.6 Package Contents

The packing box contains the following items:

(1) Hardware:

- 1 pcs. IE-703242-G1-EM1
- 1 pcs. Antistatic bag
- 6 sets Screws/washers

(2) Documentation:

- 1 pcs. Read me IE-703242-G1-EM1
- 1 pcs. Operating precautions
- 1 pcs. Hardware tool registration card
- 1 pcs. Notification on internet software update provision
- 1 pcs. Read me first
- 1 pcs. User's manual

(3) Software:

- Device Files on Floppy Disk

1.7 Connection between IE-V850ES-G1 and IE-703242-G1-EM1

The procedure for connecting the IE-V850ES-G1 and the IE-703242-G1-EM1 is shown below.

1. Disconnect the power from IE-V850-ES-G1.
2. Remove the cover of the IE-V850ES-G1.
3. Make jumper settings on main board of IE-V850ES-G1 as described in **2.3 Jumper Settings**.
4. Place the IE-703242-G1-EM1 over the main board of IE-V850ES-G1 so that the board connectors are in the correct position.
5. Press IE-703242-G1-EM1 carefully so that the connection to the main board is secured.
6. Fix the IE-703242-G1-EM1 to the main board using the screws delivered with the board.
7. If the tool is used with a target board for emulation connect the probe adapter (SWEX-100SD1) to the appropriate socket (SO2) of IE-703242-G1-EM1.
8. Close the cover of the IE-V850ES-G1.
9. Reconnect the power to the IE-V850ES-G1.
10. If the tool is used with a target board for emulation connect the target socket probe adapter to the emulation target (emulation target powered off).

Cautions: 1. **Connect carefully so as not to break or bend connector pins.**

2. **Take care to match pin 1 when connecting the probe adapter to the probe socket of IE-703242-G1-EM1.**

1.8 Power up sequence

Power on the emulation system first, then power on the target system.

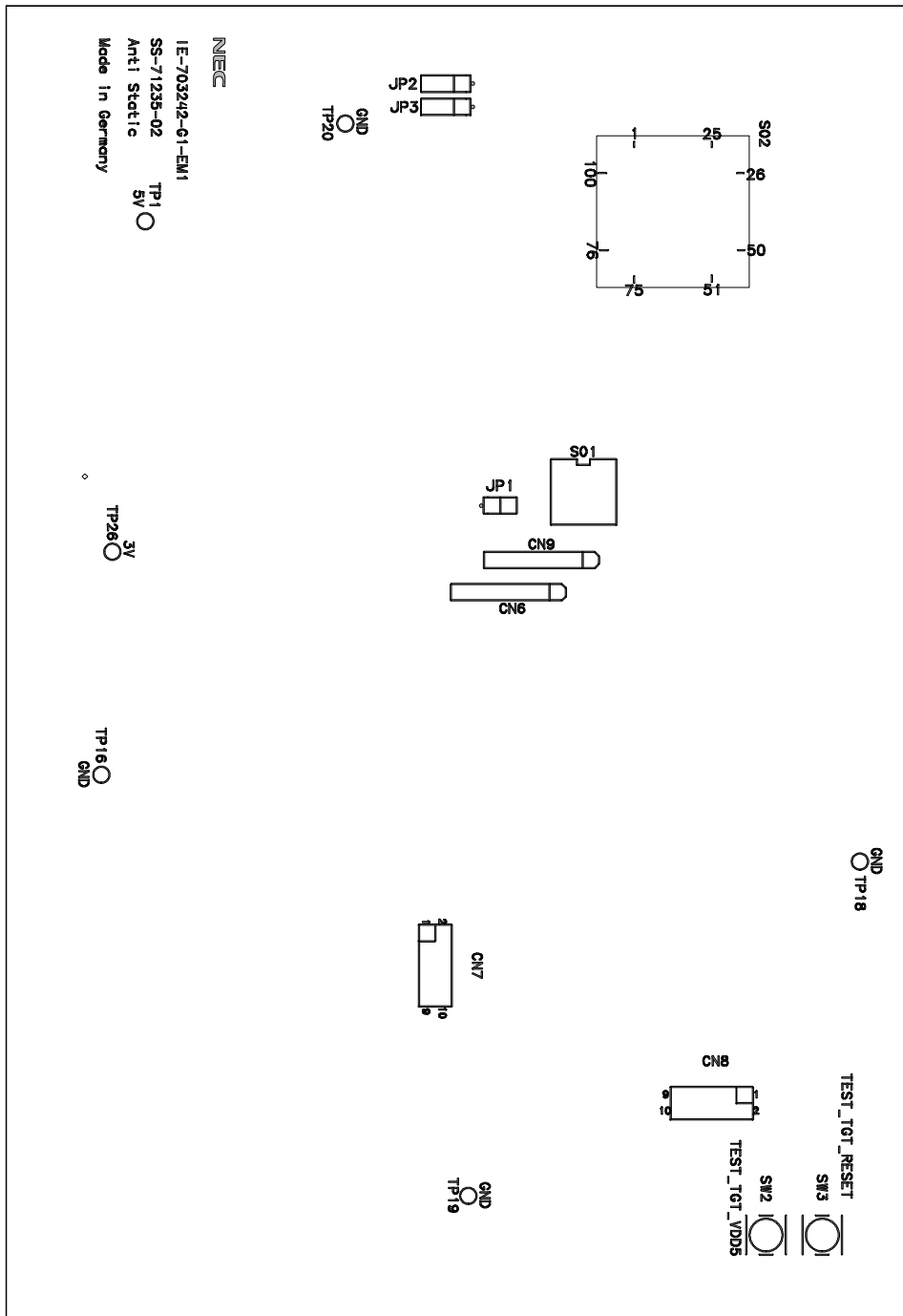
[MEMO]

Chapter 2 Name and Functions of Components

This chapter describes the names and functions of the components of IE-703242-G1-EM1. Also jumpers and switches used for configuration of the tool are described here.

2.1 Name and Functions of IE-703242-G1-EM1 Components

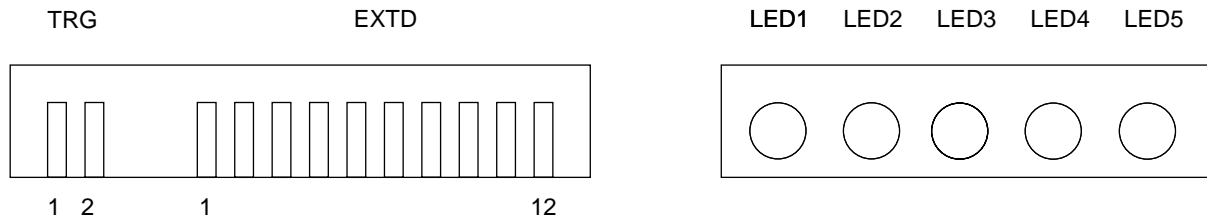
Figure 2-1: IE-703242-G1-EM1 (top view)



2.2 Status LEDs

Some of the LEDs of IE-V850ES-G1 are controlled by IE-703242-G1-EM1 to output status information. Refer to the IE-V850ES-G1 User's Manual for information on the LEDs controlled by the IE-V850ES-G1 itself.

Figure 2-3: LEDs controlled by IE-703242-G1-EM1



Remark: For information about external trigger inputs and output refer to IE-V850ES-G1 User's Manual.

Table 2-1: LEDs controlled by IE-703242-G1-EM1

LED	Colour	Function
1	green	Target reset
2	green	Don't care (internal use only)
3	green	Don't care (internal use only)
4	yellow	Target power on ^{Note}
5	red	Main Power on

Note: See 2.4 Main Sockets and Connectors for target power switching.

2.3 Jumper Settings

This chapter describes the function of the jumpers used to configure the IE-703242-G1-EM1.

2.3.1 Overview

The following table sums up the jumpers and connectors used to configure the IE-703242-G1-EM1 for the desired operation.

Table 2-2: Component Overview

Component	Function	Described in
JP1	Select sub clock signal generated by timer circuit	2.4.2 Clock Connectors
JP2	AV _{DD} input voltage selection	2.3.2 Jumper JP2: AVDD selection
JP3	AV _{SS} input voltage selection	2.3.3 Jumper JP3: AVSS selection
SO1	Socket for alternative main clock oscillator	2.4.2 Clock Connectors
SO2	Socket for target connection	2.4.1 Main Sockets
CN1, CN2, CN3	Connection to IE-V850ES-G1 emulator	2.4.1 Main Sockets
CN6	Socket for main clock crystal and capacitors	2.4.2 Clock Connectors
CN9	Socket for sub clock crystal and capacitors	2.4.2 Clock Connectors
SW2	Internal use (don't press)	-
SW3	Internal use (don't press)	-

2.3.2 Jumper JP2: AV_{DD} selection

This function is used to select the input signal for the AV_{DD} pin of the I/O chip on the IE-703242-G1-EM1 emulation board.

Table 2-3: Jumper JP2 - AV_{DD} selection

Position	Function
1-2 (default)	Connect AV _{DD} to target
2-3	Connect AV _{DD} to internal buffered 5 V supply

2.3.3 Jumper JP3: AV_{SS} selection

This function is used to select the input signal for the AV_{SS} pin of the I/O chip on the IE-703242-G1-EM1 emulation board.

Table 2-4: Jumper JP3 - AV_{SS} selection

Position	Function
1-2 (default)	Connect AV _{SS} to target
2-3	Connect AV _{SS} to GND

2.4 Main Sockets and Connectors

This chapter describes the main sockets and connectors of the IE-703242-G1-EM1. This includes sockets for connection to the IE-V850ES-G1 emulator and connections to a target board as well as connectors used for clock selection and configuration.

2.4.1 Main Sockets

The main sockets described here are used for proper installation of the IE-703242-G1-EM1 in the IE-V850ES-G1 emulator and for connection of a target board when the emulator is connected to external hardware.

Table 2-5: Main Sockets

Socket	Function
SO2	Socket is used to connect probe adapter (SWEX-100SD1) when the In-Circuit-Emulator is connected to external target hardware
CN1, CN2, CN3	Connection between the IE-703242-G1-EM1 and the IE-V850ES-G1 emulator

2.4.2 Clock Connectors

These are used to configure clock oscillators of the IE-703226-G1-MC to run at the desired operation frequency.

Table 2-6: Clock Connectors

Connector / Socket	Function
CN6	Socket for main clock crystal and capacitors
CN9	Socket for sub clock crystal and capacitors
SO1	Socket for main clock oscillator to be used alternatively instead of CN6
JP1	Select sub clock signal generated by timer circuit (alternative to CN6)

2.4.3 Other Components

Further connectors and test points are used for internal testing during production and maintenance and are not listed here.

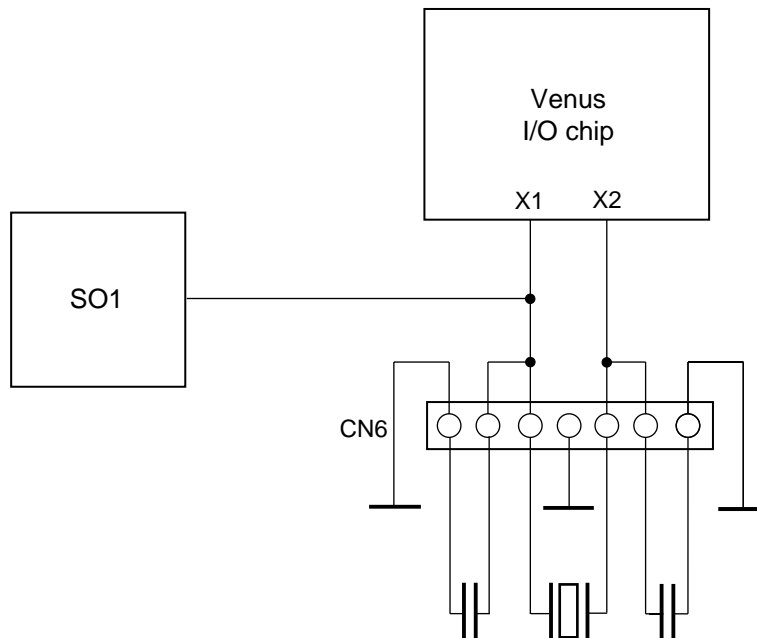
2.5 Clock Operation

This chapter describes the operation of the clock generation of IE-703242-G1-EM1. The V850ES/GB1 features two clock oscillators: a main clock oscillator for normal operation and a sub clock oscillator that allows to run the microcontroller at a slow operation speed to implement certain power save functions.

2.5.1 Main Clock

The main clock oscillator of the V850ES/GB1 and also IE-703242-G1-EM1 operates at frequencies up to 16 MHz. On the emulation board the source for the main clock can either be a crystal or a dedicated C-MOS oscillator. By default a crystal is used which is assembled to the respective connector (CN6). Alternatively a dedicated C-MOS oscillator in DIL Package may be used. In this case the crystal and capacitors must be removed from CN6 and a crystal oscillator must be mounted to socket SO1.

Figure 2-4: Main Clock Configuration



Caution: Since the clock inputs X1 and X2 of the I/O chip are not connected to the target, crystal or oscillator operation from the target board is not possible. Crystal or Oscillator provided on the emulation board must be used.

2.5.2 Sub Clock

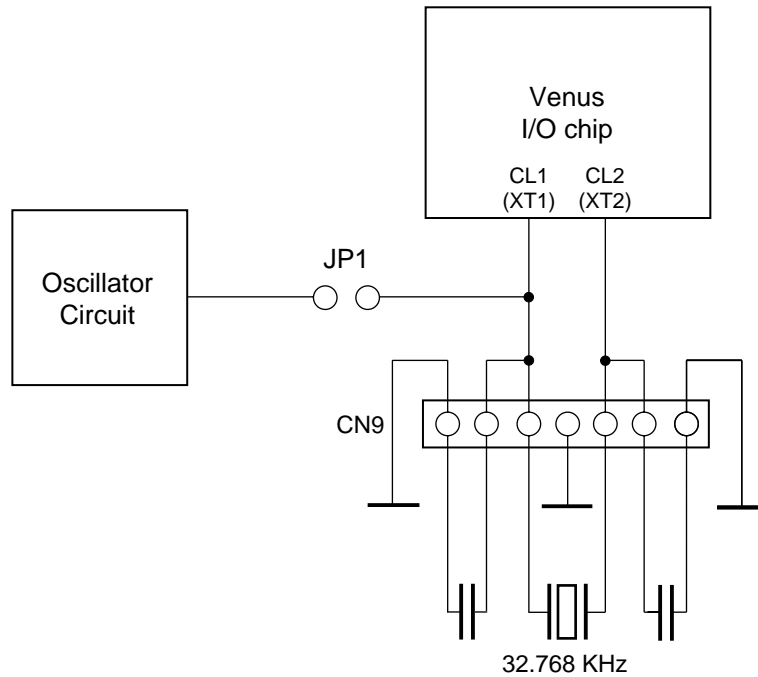
The V850ES/GB1 is available in different versions that feature different sub clock oscillators for device operation at low frequencies:

- Crystal oscillator
- RC oscillator

If a crystal oscillator is used for the sub clock oscillator, a crystal of a fixed frequency of 32.768 KHz and capacitors must be connected to the connector CN9.

For emulation of the RC oscillator a dedicated timer circuit on the emulation board can be used. This timer circuit generates an adjustable frequency in the range of 40 to 100 KHz. If the timer circuit is used the sub clock crystal and capacitors must be disconnected from CN9 and jumper JP1 must be shorted. By default the timer circuit is configured to operate at a frequency of about 100 KHz. To adjust the operating frequency of the sub clock timer circuit R28, R29 and C77 on the emulation board must be changed.

Figure 2-5: Sub Clock Configuration



Caution: Since the clock inputs CL1 and CL2 (XT1 and XT2 respectively) are not connected to the target, crystal or RC oscillator operation from the target board is not possible. Crystal or RC oscillator provided on the emulation board must be used.

Chapter 2 Name and Functions of Components

To change the operation frequency of the oscillator circuit R28, R29 and C77 must be selected using the following formulae:

$$f = \frac{1.44}{(R28 + 2 \cdot R29) \cdot C77}$$

$$R29 = \frac{1}{2} \cdot \left(\frac{1.44}{f \cdot C77} - R28 \right)$$

Remark: Use R28 and R29 in the Range $1 \text{ K}\Omega < R < 10 \text{ M}\Omega$ and C77 in the Range $1 \text{ nF} < C < 10 \text{ }\mu\text{F}$.

[MEMO]

Chapter 3 Operating Precautions

Be aware of the following operating precautions when using the IE-703242-G1-EM1.

3.1 Reset source monitor flag

The reset source (reset caused by external reset input or watchdog timer) can not be distinguished by the RSM register of the clock controller during emulation mode. Oscillation stabilization time is skipped after a watchdog timer reset during sub watch mode.

3.2 Standby release

The main oscillator of the V850ES/GB1 I/O chip on the emulation board is always running and can not be switched off. Therefore no oscillation stabilization time is required when stop mode or sub watch mode of V850ES/GB1 is released. As a consequence of this the V850ES/GB1 I/O chip on the ICE will wake up immediately from sub watch or stop mode whereas the V850ES/GB1 real chip always assures the oscillation stabilization time for the main oscillator when standby mode is released.

3.3 Port direction setting for peripheral function

When a peripheral function is used the direction setting for the respective port bit of the V850ES/GB1 real chip is not set automatically. The port bit direction has to be programmed according to the requirement of the peripheral function by setting the port mode register. In the FPGA on the emulation board port mode setting is not necessary when a peripheral function is used. Therefore on the emulator ports emulated by the FPGA behave different from the real chip. This only affects bit 1 of port PCM, CLOCKOUT function. Therefore if the CLOCKOUT function is to be used the respective bit positions of registers PMCM and PMCCM have to be set accordingly.

3.4 Programmable peripheral area

The usable settings for the BPC register limit usage to the first 32MB of the total address range. Therefore the programmable peripheral area must be set to an address range within the first 32 MB.

3.5 Other precautions

Take note of the differences between the In-Circuit Emulator and the real chip described in **Chapter 4 Differences between Target Device and Emulation Board.**

[MEMO]

Chapter 4 Differences between Target Device and Emulation Board

When the In-Circuit-Emulator is connected to a target system for debugging, the V850ES/GB1 is emulated which means that the emulator behaves like the real chip in the target system. Small differences occur however. This chapter lists differences between the emulation system and the V850ES/GB1.

4.1 BCU (bus control unit)

The BCU is established within an FPGA. Therefore this could be slightly different to the real chip.

4.2 Load on voltage supply pins

The I/O chip is supplied by a power supply on the emulation board. Therefore the load on the power supply of the target board is very low compared to the real chip.

4.3 Reset input

The reset pin of the target connector is not connected to the reset pin of the I/O chip directly. It also has got a 10 K Ω pull-up resistor connected to it. The input characteristic differs from the real chip.

4.4 REGC pin

The REGC pin of the target connector is not connected to the corresponding pin of the I/O chip. On the emulation board a capacitor is connected to the REGC pin of the I/O chip internally.

4.5 Clock oscillator inputs

The pins for main clock connection (X1 and X2) as well as the pins for sub clock connection (CL1, CL2 / XT1, XT2) of the I/O chip on the emulation board are not connected to the target connector. If a crystal is to be used for the clock generator it must be connected to the respective connector on the emulation board which is located electrically close to the I/O chip. Crystal operation from the target board is not possible. Alternatively a dedicated C-MOS oscillator can be used for the main clock and a timer circuit provided on the emulation board can be used for the sub clock (See also **2.5 Clock Operation**).

4.6 V_{PP} pin

V_{PP} pin of the I/O chip on the emulation board is connected to the target connector with a load of 10 K Ω (series resistor). On the emulation board it is only monitored and not used internally. Correct connection on the target board must be assured.

4.7 AV_{DD}, AV_{SS} pins

AV_{DD} and AV_{SS} pins of the I/O chip on the emulation board can be disconnected from the target connector. ADC values and the load on AV_{DD} and AV_{SS} pins may differ in that case.

Table 4-1: Pin list according to their emulation location (1/3)

100 Pin	Top pin name	Pin Function	default I/O single chip		Emulated by Venus chip	Emulated by FPGA via Level Shifter	Alternative connected to:
1	AV _{DD}	AV _{DD}	S		Venus		internal
2	AV _{SS}	AV _{SS}	S		Venus		internal
3	P00	P00/INTP0	I		Venus		
4	P01	P01/INTP1	I		Venus		
5	P02	P02/INTP2	I		Venus		
6	P03	P03/INTP3	I		Venus		
7	P04	P04/INTP4	I		Venus		
8	P05	P05/INTP5	I		Venus		
9	V _{DD50}	V _{DD50}	S				buffered
10	REGC0	REGC0	S				not connected
11	V _{SS30}	V _{SS30}	S				Ground
12	X1	X1	I				not connected
13	X2	X2	O				not connected
14	RESET	RESET	I				buffered
15	XT1	XT1	I				not connected
16	XT2	XT2	O				not connected
17	NMI	NMI	I		Venus		
18	P06	P06/INTP6	I		Venus		
19	P10	P10/SI00	I		Venus		
20	P11	P11/SO00	I		Venus		
21	P12	P12/SCK00	I		Venus		
22	P13	P13/RXD60/INTP7	I		Venus		
23	P14	P14/TXD60	I		Venus		
24	P15	P15	I		Venus		
25	P40	P40/KR0	I		Venus		
26	P41	P41/KR1/TIG00	I		Venus		
27	P42	P42/KR2/TIG01/TOG01	I		Venus		
28	P43	P43/KR3/TIG02/TOG02	I		Venus		
29	P44	P44/KR4/TIG03/TOG03	I		Venus		
30	P45	P45/KR5/TIG04/TOG04	I		Venus		
31	P46	P46/KR6/TIG05	I		Venus		
32	P47	P47/KR7	I		Venus		
33	P50	P50	I		Venus		

Table 4-1: Pin list according to their emulation location (2/3)

100 Pin	Top pin name	Pin Function	default I/O single chip		Emulated by Venus chip	Emulated by FPGA via Level Shifter	Alternative connected to:
34	P51	P51	I		Venus		
35	P52	P52	I		Venus		
36	P53	P53	I		Venus		
37	P54	P54/DCTXD0	I		Venus		
38	P55	P55/DCRXD0	I		Venus		
39	P56	P56	I		Venus		
40	P57	P57	I		Venus		
41	PCS0	PCS0	I			FPGA via L/S	
42	PCS1	PCS1	I			FPGA via L/S	
43	PDL0	PDL0	I			FPGA via L/S	
44	PDL1	PDL1	I			FPGA via L/S	
45	PDL2	PDL2	I			FPGA via L/S	
46	PDL3	PDL3	I			FPGA via L/S	
47	PDL4	PDL4	I			FPGA via L/S	
48	PDL5	PDL5	I			FPGA via L/S	
49	PDL6	PDL6	I			FPGA via L/S	
50	PDL7	PDL7	I			FPGA via L/S	
51	PDL8	PDL8	I			FPGA via L/S	
52	PDL9	PDL9	I			FPGA via L/S	
53	PDL10	PDL10	I			FPGA via L/S	
54	PDL11	PDL11	I			FPGA via L/S	
55	PDL12	PDL12	I			FPGA via L/S	
56	PDL13	PDL13	I			FPGA via L/S	
57	V _{PP}	V _{PP}	S				not connected
58	PDL14	PDL14	I			FPGA via L/S	
59	PDL15	PDL15	I			FPGA via L/S	
60	V _{DD51}	V _{DD51}	S				buffered
61	V _{SS51}	V _{SS51}	S				Ground
62	PCM0	PCM0	I			FPGA via L/S	
63	PCM1	PCM1, CLOCKOUT	I			FPGA via L/S	
64	PCM2	PCM2	I			FPGA via L/S	
65	V _{SS31}	V _{SS31}	S				Ground
66	REGC1	REGC1	S				not connected
67	PCM3	PCM4	I			FPGA via L/S	
68	PDH0	PDH0	I			FPGA via L/S	
69	PDH1	PDH1	I			FPGA via L/S	
70	PDH2	PDH2	I			FPGA via L/S	
71	PDH3	PDH3	I			FPGA via L/S	
72	PDH4	PDH4	I			FPGA via L/S	

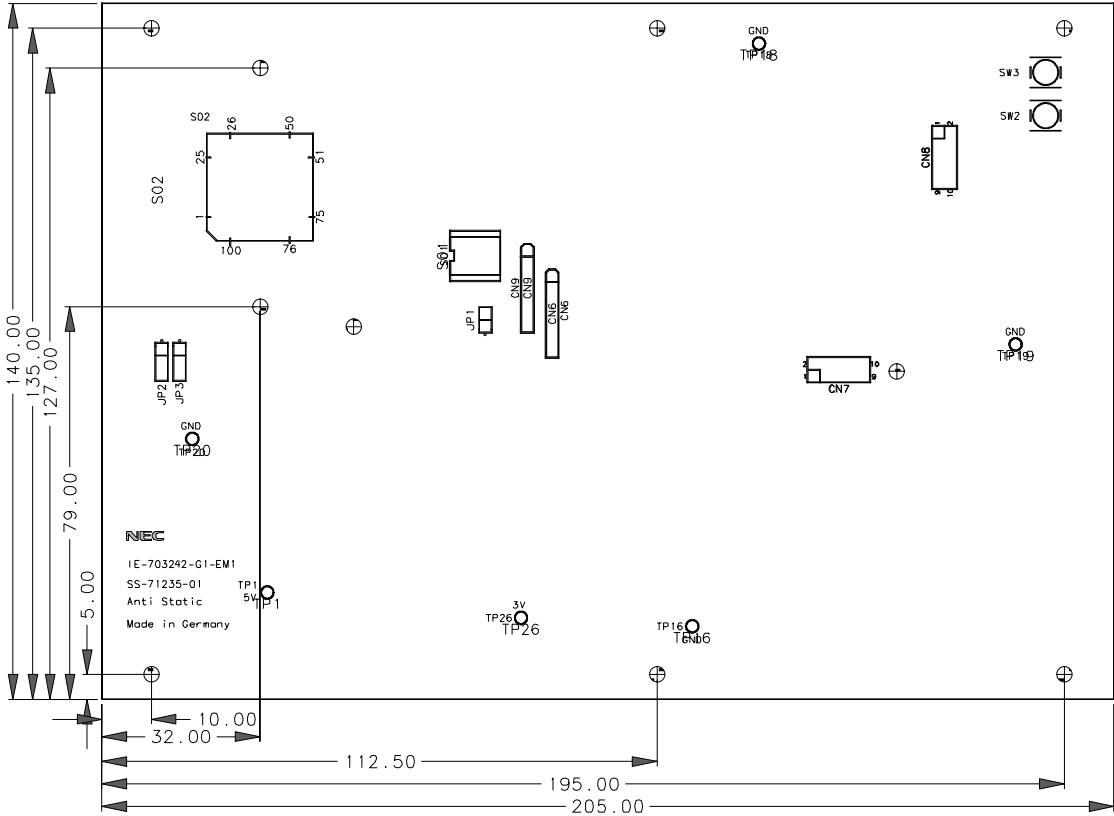
Chapter 4 Differences between Target Device and Emulation Board

Table 4-1: Pin list according to their emulation location (3/3)

100 Pin	Top pin name	Pin Function	default I/O single chip		Emulated by Venus chip	Emulated by FPGA via Level Shifter	Alternative connected to:
73	PDH5	PDH5	I			FPGA via L/S	
74	PCT0	PCT0	I			FPGA via L/S	
75	PCT1	PCT1	I			FPGA via L/S	
76	PCT4	PCT4	I			FPGA via L/S	
77	PCT6	PCT6	I			FPGA via L/S	
78	P20	P20/RXD61/INTP8	I		Venus		
79	P21	P21/TXD61	I		Venus		
80	P22	P22/SI01	I		Venus		
81	P23	P23/SO01	I		Venus		
82	P24	P24/ $\overline{\text{SCK01}}$	I		Venus		
83	P25	P25	I		Venus		
84	P30	P30/TI50/TO50	I		Venus		
85	P31	P31/TI51/TO51	I		Venus		
86	P32	P32/TI52/TO52	I		Venus		
87	P33	P33/TIC00/TOC0	I		Venus		
88	P34	P34/TIC01	I		Venus		
89	P711	P711/ANI11	I		Venus		
90	P710	P710/ANI10	I		Venus		
91	P79	P79/ANI9	I		Venus		
92	P78	P78/ANI8	I		Venus		
93	P77	P77/ANI7	I		Venus		
94	P76	P76/ANI6	I		Venus		
95	P75	P75/ANI5	I		Venus		
96	P74	P74/ANI4	I		Venus		
97	P73	P73/ANI3	I		Venus		
98	P72	P72/ANI2	I		Venus		
99	P71	P71/ANI1	I		Venus		
100	P70	P70/ANI0	I		Venus		

Appendix A Mechanical Data

Figure A-1: Mechanical Data



[MEMO]

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